

Taiwan TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee

Liaison Report
Aug. 13, 2021

Meeting Information



- Last meeting
 - August 13, 2021 at the SEMI Standards Taiwan Summer 2021 Meetings
 - Virtual Meeting, OVTCCM
- Next meeting
 - March. 4, 2022 at the SEMI Standards Taiwan Spring 2021 Meetings
 - Virtual Meeting, OVTCCM

Leadership

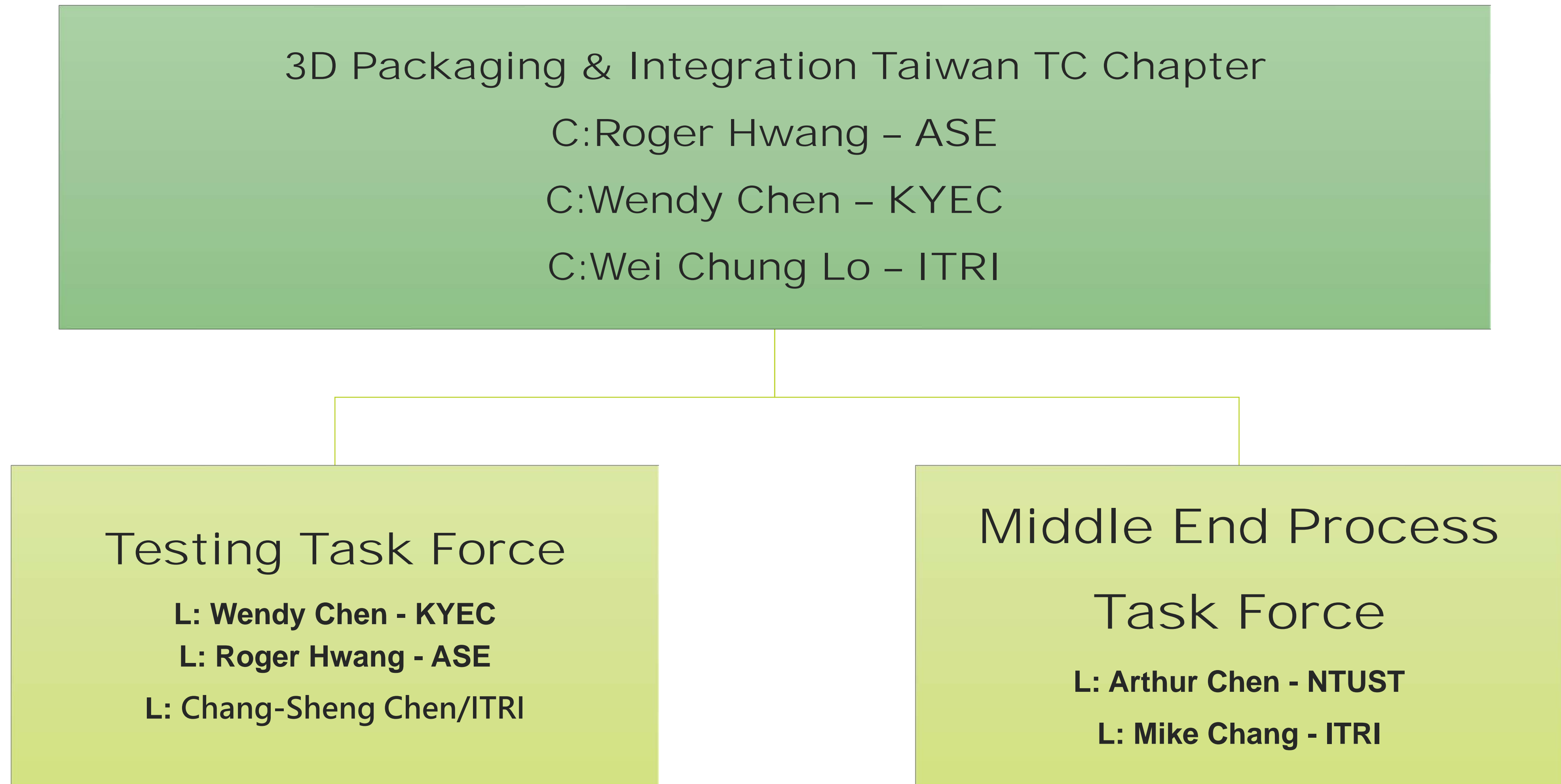
Co-chairs

- **Wei-Chung Lo – ITRI**
- **Wendy Chen - King Yuan Electronics Company**
- **Roger Hwang - ASE**

Leadership Changes

None

Organization Chart



Ballot Results



Doc #	Document Title	TC Chapter Action
None		

Authorized Activities



#	Type	SC/TF/WG	Details
TBD	SNARF	Testing Task Force	Line Item Revision to SEMI 3D14-0615 Guide for Incoming/Outgoing Quality control and Testing Flow for 3DSIC Products
TBD	SNARF	Middle End Process Task Force	Reapproval of SEMI 3D15-0316 Guide for Overlay Performance Assessment for 3DS-IC Process.

Authorized Ballots



#	When	TF	Details
TBD	Cycle 7 or 8, 2021	Testing Task Force	Line Item Revision to SEMI 3D14-0615 Guide for Incoming/Outgoing Quality control and Testing Flow for 3DSIC Products
TBD	Cycle 7 or 8, 2021	Middle End Process Task Force	Reapproval of SEMI 3D15-0316 Guide for Overlay Performance Assessment for 3DS-IC Process.

Abolished SNARF(s)



Doc #	TF	Title/Details
None		

Task Force Highlights (1/2)



- **Testing Task Force**

- ✓ Leader Ship Change

- L: Wendy Chen - KYEC

- L: Roger Hwang - ASE

- L: Shang-Chun Chen – ITRI changed to Chang-Sheng Chen/ITRI

- ✓ New Business

- Over 5 years review by TF, Scheduled to get new doc. # for Line Item Change
3D14-0615 Guide for Incoming/Outgoing Quality control and Testing Flow

- New topic direction discussion : Chip testing before stacking: standard CCC might not be sufficient, consider to introduce MAC to protect both the chip and probe, and its testing temperature condition
Action Item : TF Co-leaders work with SEMI Staff to invite Probe card players to kick off meeting at the end of September.

Task Force Highlights (2/2)



- **Middle End Process Task Force**

- ✓ Leader Ship

- L: Arthur Chen - NTUST

- L: Mike Chang - ITRI

- ✓ New Business

- Over 5 years review , Scheduled to get new doc. # for reapproval

- SEMI 3D15-0316 Guide for Overlay Performance Assessment for 3DS-IC Process

- Study the feasibility of submitting a new SNARF for CMP standards in the next TC meeting.

Thank you

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